



## **Intermolecular to Present at 2016 Flash Memory Summit on How High-Throughput Experimentation Can Identify the Most Promising Memory Selectors For 3D Cross-Point Non Volatile Memories**

**SAN JOSE, Calif. – August 9, 2016** – [Intermolecular, Inc.](#) (NASDAQ: IMI), the trusted partner in materials innovation, today announced it will present at the [Flash Memory Summit](#) on Thursday, August 11, 2016, at 8.30 am during the session 301-C: Intel-Micron 3D Xpoint™: The Next Generation Non-Volatile Memory (New Technologies Track).

Milind Weiling, Vice President for Electronic Applications at Intermolecular, will cover the challenges in vertically stackable selectors for 3D Cross-Point Non Volatile Memories and propose a development methodology using high-throughput physical vapor deposition (PVD) and test-based experimentation to identify the most promising selector characteristics and potential material systems.

In addition, Intermolecular will chair an open roundtable session where participants can discuss developments in RRAM during the Expert at the Table Session on Tuesday, August 9, from 7:00pm to 8:30 p.m. PST.

### **About Intermolecular, Inc.**

Intermolecular® is the trusted partner for advanced materials innovation. Advanced materials are at the core of innovation in the 21<sup>st</sup> century for a wide range of industries including semiconductors, consumer electronics, automotive and aerospace. With its substantial materials expertise; accelerated learning and experimentation platform; and information and analytics infrastructure, Intermolecular has a ten-year track record helping leading companies accelerate and de-risk materials innovation.

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